2.5 V, 3 V, 3.3 V, 5 V

Delay Time of 200 ms

GND

RESET

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Precision Supply Voltage Monitor

Power-On Reset Generator With Fixed

Pin-For-Pin Compatible With MAX 809

2

TPS3809 ... DBV PACKAGE (TOP VIEW)

3

VDD

- Qualified for Automotive Applications
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Using Human Body Model (C = 100 pF, R = 1500 Ω)
- 3-Pin SOT-23 Package
- Supply Current of 9 μA (Typical)

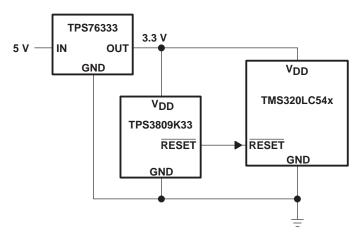
description

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage V_{DD} becomes higher than 1.1 V.

Thereafter, the supervisory circuit monitors V_{DD} and keeps RESET active as long as V_{DD} remains below the threshold voltage V_{IT} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_{d(typ)} = 200$ ms, starts after V_{DD} has risen above the threshold voltage V_{IT} . When the supply voltage drops below the threshold voltage V_{IT} , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed sense-threshold voltage V_{IT} set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23. The TPS3809xxxQ-Q1 devices are characterized for operation over a temperature range of -40°C to 125°C, and are qualified in accordance with AEC-Q100 stress test qualification for integrated circuits.



typical applications

- Applications Using Automotive DSPs, Microcontrollers, or Microprocessors
- Wireless Communication Systems
- Battery-Powered Equipment
- Programmable Controls
- Intelligent Instruments
- Industrial Equipment
- Automotive Systems



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| AVAILABLE OPTIONS ^{†‡} | | | | | | | |
|----------------------------------|--|--|--|--|--|--|--|
| TA DEVICE NAME THRESHOLD VOLTAGE | | | | | | | |
| TPS3809J25QDBVRQ1§ | 2.25 V | PCZQ | | | | | |
| TPS3809L30QDBVRQ1§ | 2.64 V | PDAQ | | | | | |
| TPS3809K33QDBVRQ1§ | 2.93 V | PDBQ | | | | | |
| TPS3809I50QDBVRQ1§ | 4.55 V | PDCQ | | | | | |
| | DEVICE NAME TPS3809J25QDBVRQ1 TPS3809L30QDBVRQ1 TPS3809K33QDBVRQ1 | DEVICE NAME THRESHOLD VOLTAGE TPS3809J25QDBVRQ1\$ 2.25 V TPS3809L30QDBVRQ1\$ 2.64 V TPS3809K33QDBVRQ1\$ 2.93 V | | | | | |

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at http://www.ti.com.

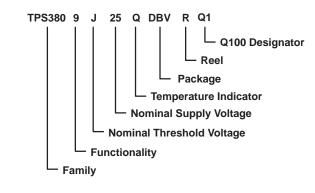
[‡]Package drawings, thermal data, and symbolization are available at http://www.ti.com/packaging.

§ The DBVR passive indicates tape and reel of 3000 parts.

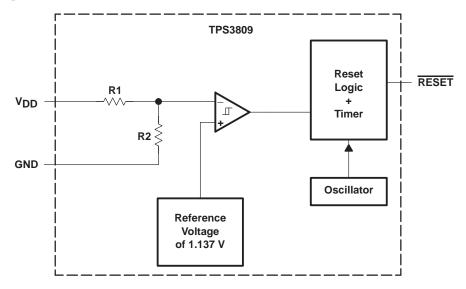
FUNCTION/TRUTH TABLE, TPS3809

| V _{DD} >V _{IT} | RESET |
|----------------------------------|-------|
| 0 | L |
| 1 | н |

ORDERING INFORMATION



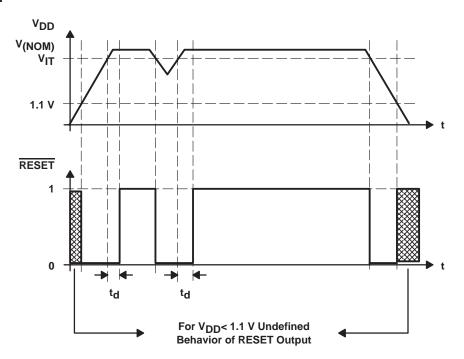
functional block diagram





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timing diagram



absolute maximum ratings over operating free-air temperature (unless otherwise noted)[†]

| Supply voltage, V _{DD} (see Note1) | |
|---|------------------------------|
| All other pins (see Note 1) | \ldots –0.3 V to 7 V |
| Maximum low output current, I _{OL} | 5 mA |
| Maximum high output current, IOH | –5 mA |
| Input clamp current, I _{IK} (VI<0 or VI>VDD) | ±20 mA |
| Output clamp current, I _{OK} (V _O <0 or V _O >V _{DD}) | ±20 mA |
| Continuous total power dissipation | See Dissipation Rating Table |
| Operating free-air temperature range, T _A | –40°C to 125°C |
| Storage temperature range, T _{stg} | –65°C to 150°C |
| Soldering temperature | |
| | |

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute–maximum–rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation the device should not be operated at 7 V for more than t=1000h continuously.

| DISSIPATION | RATING | TABI F |
|-------------|----------|--------|
| | INALINO. | INDLL |

| PACKAGE | T _A <25°C | DERATING FACTOR | T _A = 70°C | T _A = 85°C | T _A = 125°C |
|---------|----------------------|-----------------------------|-----------------------|-----------------------|------------------------|
| | POWER RATING | ABOVE T _A = 25°C | POWER RATING | POWER RATING | POWER RATING |
| DBV | 437 mW | 3.5 mW/°C | 280 mW | 227 mW | 87 mW |

recommended operating conditions at specified temperature range

| | MIN | MAX | UNIT |
|--|-----|-----|------|
| Supply voltage, V _{DD} | 2 | 6 | V |
| Operating free-air temperature range, T _A | -40 | 125 | °C |



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT | |
|------------------|---|--|--|---------------------------------------|----------------------|------|------|------|
| | | | V_{DD} = 2.5 V to 6 V, I_{OH} = -500 μ A | | V _{DD} -0.2 | | | |
| | V _{OH} High-level output voltage | | $V_{DD} = 3.3 \text{ V}, \qquad I_{OH} = -2 \text{ mA}$ | | V _{DD} -0.4 | | | |
| VOH | | | | $T_A = -40^{\circ}C$ to $25^{\circ}C$ | V _{DD} -0.4 | | | V |
| | | | $V_{DD} = 6 V$, $I_{OH} = -4 mA$ | T _A = 125°C | V _{DD} -0.5 | | | |
| | | | $V_{DD} = 2 V \text{ to } 6 V$, $I_{OL} = 5$ | 500 μΑ | | | 0.2 | |
| VOL | Low-level output voltag | e | V _{DD} = 3.3 V, I _{OL} = 2 | 2 mA | | | 0.4 | V |
| | | | $V_{DD} = 6 V$, $I_{OL} = 4$ | 1 mA | | | 0.4 | |
| | Power-up reset voltage | e (see Note 2) | $V_{DD} \ge 1.1 \text{ V}, \qquad I_{OL} = 50 \mu\text{A}$ | | | | 0.2 | V |
| Negative-goin | | TPS3809J25 | | | 2.20 | 2.25 | 2.30 | |
| | Negative-going input | TPS3809L30 | $T_{A} = -40^{\circ}C$ to 125°C | | 2.58 | 2.64 | 2.70 | |
| VIT− | threshold voltage | reshold voltageTPS3809K33ee Note 3) $T_{\Delta} = -40^{\circ}C$ to $85^{\circ}C$ | | 2.87 | 2.93 | 2.99 | V | |
| | (see Note 3) | | $T_A = -40^{\circ}C$ to $85^{\circ}C$ | | 4.45 | 4.55 | | 4.65 |
| | | TPS3809I50 | $T_A = -40^{\circ}C$ to $125^{\circ}C$ | | 4.4 | 4.55 | | 4.65 |
| | | TPS3809J25 | | | | 30 | | |
| ., | | TPS3809L30 | | | | 35 | | |
| V _{hys} | Hysteresis | /steresis TPS3809K33 | | | 40 | | mV | |
| | | TPS3809I50 | | | | 60 | | |
| | | $V_{DD} = 2 V$, Output unconr | nected | | 9 | 15 | | |
| IDD | Supply current | | $V_{DD} = 6 V$, Output unconnected | | | 20 | 30 | μA |
| Ci | Input capacitance | | $V_{I} = 0 V \text{ to } V_{DD}$ | | | 5 | | pF |

NOTES: 2. The lowest supply voltage at which $\overline{\text{RESET}}$ becomes active. $t_{r, VDD} \ge 15 \,\mu\text{s/V}$.

3. To ensure best stability of the threshold voltage, a bypass capacitor (0.1 µF ceramic) should be placed near the supply terminals.

timing requirements at R_L = 1 M Ω , C_L = 50 pF, T_A = 25°C

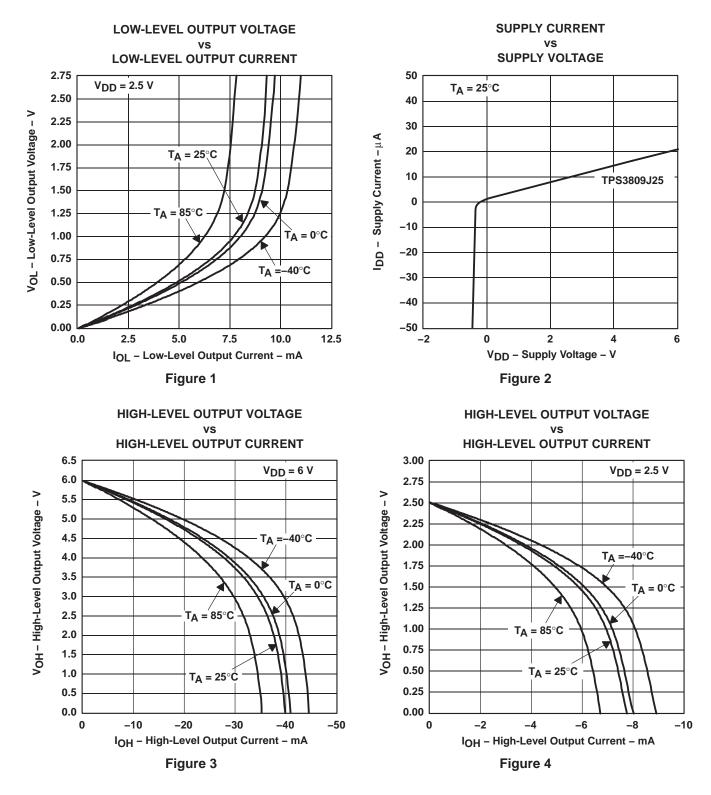
| | PARAMETER | | ٢ | MIN | TYP | MAX | UNIT | |
|----|-------------|--------------------|-----------------------------|----------------------------|-----|-----|------|----|
| tw | Pulse width | at V _{DD} | $V_{DD} = V_{IT-} + 0.2 V,$ | $V_{DD} = V_{IT-} - 0.2 V$ | 3 | | | μs |

switching characteristics at RL = 1 MΩ, CL = 50 pF, TA = 25°C

| | PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT | |
|------------------|--|--|---|-----|-----|------|----|
| td | Delay time | $V_{DD} \ge V_{IT-} + 0.2 V$, See timing diagram | 120 | 200 | 280 | ms | |
| ^t PHL | Propagation (delay) time, high-to-low-level output | V _{DD} to RESET delay | $V_{IL} = V_{IT-} - 0.2 V,$ $V_{IH} = V_{IT-} + 0.2 V$ | | 1 | | μs |



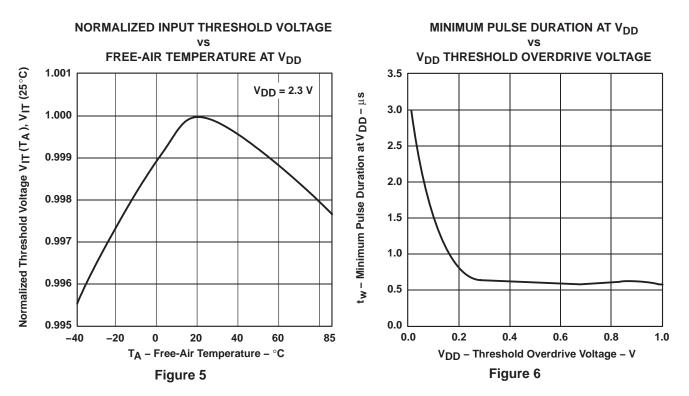
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TYPICAL CHARACTERISTICS



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TYPICAL CHARACTERISTICS



JMENTS www ti com

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|--------------------|-----------------------|-----------------|--------------------|------|----------------|----------------------------|------------------|------------------------------|
| 2T09I50QDBVRG4Q | ACTIVE | SOT-23 | DBV | 3 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 2T09J25QDBVRG4Q | ACTIVE | SOT-23 | DBV | 3 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 2U3809K33QDBVRG4Q1 | ACTIVE | SOT-23 | DBV | 3 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| 2U3809L30QDBVRG4Q1 | ACTIVE | SOT-23 | DBV | 3 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS3809I50QDBVRQ1 | ACTIVE | SOT-23 | DBV | 3 | 3000 | TBD | CU NIPDAU | Level-1-220C-UNLIM |
| TPS3809J25QDBVRQ1 | ACTIVE | SOT-23 | DBV | 3 | 3000 | TBD | CU NIPDAU | Level-1-220C-UNLIM |
| TPS3809K33QDBVRQ1 | ACTIVE | SOT-23 | DBV | 3 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS3809L30QDBVRQ1 | ACTIVE | SOT-23 | DBV | 3 | 3000 | TBD | CU NIPDAU | Level-1-220C-UNLIM |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL. Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TPS3809I50-Q1, TPS3809J25-Q1, TPS3809K33-Q1, TPS3809L30-Q1 :

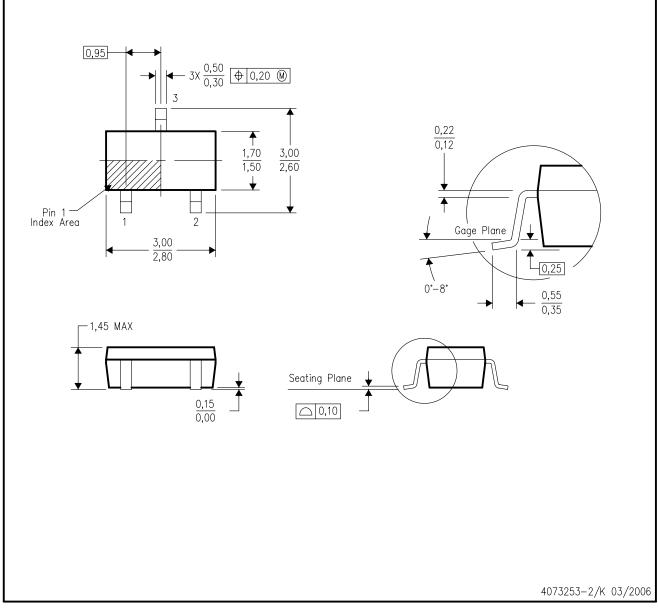
• Catalog: TPS3809I50, TPS3809J25, TPS3809K33, TPS3809L30 • Enhanced Product: TPS3809I50-EP, TPS3809K33-EP, TPS3809L30-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

DBV (R-PDSO-G3)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.



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